



Specification of Automotive MLCC

• Supplier : Samsung electro-mechanics • Samsung P/N : CL21B223KB65PNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 22nF, 50V, ±10%, X7R, 0805

• AEC-Q 200 Specified

A. Samsung Part Number

<u>CL</u> <u>21</u> <u>B</u> <u>223</u> <u>K</u> <u>B</u> <u>6</u> <u>5</u> <u>P</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor				
2	Size	0805 (inch code)	L:	$2.0 \pm 0.1 \text{ mm}$	W:	1.25 ± 0.1 mm
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3	Dielectric	X7R		8 Inner electrode		Ni , Open mode
4	Capacitance	22 nF		Termination		Cu , Ag-epoxy
(5)	Capacitance	±10 %		Plating		Sn 100% (Pb Free)
	tolerance			9 Product		Automotive
6	Rated Voltage	50 V		Grade code		Standard
7	Thickness	0.6 ± 0.1 mm		11 Packaging		Cardboard Type, 7" reel

B. Reliablility Test and Judgement condition

	Performance	Test condition		
High Temperature	Appearance : No abnormal exterior appearance	Unpowered, 1000hrs@T=150℃		
Exposure	Capacitance Change : Within ±10%	Measurement at 24±2hrs after test conclusion		
	Tan δ : 0.03 max			
	IR : More than 10,000⋒Ω or 500⋒Ω× <i>μ</i> F			
	Whichever is Smaller			
Temperature Cycling	Appearance : No abnormal exterior appearance	1000Cycles		
	Capacitance Change : Within ±10%	Measurement at 24±2hrs after test conclusion		
	Tan δ : 0.03 max	1 cycle condition :		
	IR : More than 10,000№ or 500№×μF	-55+0/-3℃(15±3min) -> Room Temp(1min.)		
	Whichever is Smaller	-> 125+3/-0 ℃ (15±3min) -> Room Temp(1min.)		
Destructive Physical No Defects or abnormalities		Per EIA 469		
Analysis				
Moisture Resistance	Appearance : No abnormal exterior appearance	10Cycles, t=24hrs/cycle		
	Capacitance Change : Within ±12.5%	Heat (25~65℃) and humidity (80~98%), Unpowered		
	Tan δ : 0.03 max	measurement at 24±2hrs after test conclusion		
	IR : More than 10,000⋒Ω or 500⋒Ω× <i>μ</i> F			
	Whichever is Smaller			
Humidity Bias	Appearance : No abnormal exterior appearance	1000hrs 85℃/85%RH, Rated Voltate and 1.3~1.5V,		
	Capacitance Change : Within ±12.5%	Add 100kohm resistor		
	Tan δ : 0.035 max	Measurement at 24±2hrs after test conclusion		
	IR : More than 500MΩ or 25MΩ×μF	The charge/discharge current is less than 50mA.		
	Whichever is Smaller			
High Temperature	Appearance : No abnormal exterior appearance	1000hrs @ TA=125℃, 200% Rated Voltage,		
Operating Life	Capacitance Change : Within ±12.5%	Measurement at 24±2hrs after test conclusion		
	Tan δ : 0.035 max	The charge/discharge current is less than 50mA.		
	IR : More than 1000MΩ or 50MΩ×μF			
	Whichever is Smaller			

	Performance	Test condition				
External Visual No abnormal exterior appearance		Microscope ('10)				
Physical Dimensions	Within the specified dimensions	Using The calipers				
Mechanical Shock	Appearance : No abnormal exterior appearance Capacitance Change : Within ±10% Tan δ, IR : initial spec.	Three shocks in each direction should be applied along 3 mutually perpendicular axes of the test specimen (18 shocks) Peakvalue Duration Wave Velocity 1,500G 0.5ms Half sine 4.7m/sec.				
Vibration	Appearance : No abnormal exterior appearance Capacitance Change : Within ±10% Tan δ, IR : initial spec.	5g's for 20min., 12cycles each of 3 orientations, Use 8"×5" PCB 0.031" Thick 7 secure points on one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10~2000Hz.				
Resistance to Solder Heat	Appearance : No abnormal exterior appearance Capacitance Change : Within ±10% Tan δ, IR : initial spec.	Solder pot : 260±5℃, 10±1sec.				
Thermal Shock	Appearance : No abnormal exterior appearance Capacitance Change : Within ±10% Tan δ, IR : initial spec.	-55°C/+125°C. Note: Number of cycles required-300, Maximum transfer time-20 sec, Dwell time-15min. Air-Air				
ESD	Appearance : No abnormal exterior appearance Capacitance Change : Within ±10% Tan δ, IR : initial spec.	AEC-Q200-002				
Solderability	95% of the terminations is to be soldered evenly and continuously	a) Preheat at 155°C for 4 hours, Immerse in solder for 5s at 245±5°C b) Steam aging for 8 hours, Immerse in solder for 5s at 245±5°C c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5°C solder: a solution ethanol and rosin				
Electrical Characterization	Capacitance: Within specified tolerance Tan δ (DF): 0.025 max. IR(25°C): More than 10,000μΩ or 500μΩ×μF IR(125°C): More than1,000μΩ or 10μΩ×μF Whichever is Smaller Dielectric Strength	The Capacitance /D.F. should be measured at 25°C, 1½±10%, 1.0±0.2Vrms I.R. should be measured with a DC voltage not exceeding Rated Voltage @25°C, @125°C for 60~120 sec. Dielectric Strength: 250% of the rated voltage for 1~5 seconds				
Board Flex	Appearance : No abnormal exterior appearance Capacitance Change : Within ±10%	Bending to the limit (2mm) for 5 seconds				
Terminal Strength(SMD)	Appearance : No abnormal exterior appearance Capacitance Change : Within ±10%	18N, for 60±1 sec.				
Beam Load	Destruction value should not be exceed Chip Length < 2.5mm a) Chip Thickness > 0.5mm : 20N b) Chip Thickness ≤ 0.5mm : 8N	Beam speed 0.5±0.05mm/sec				
Temperature Characterisitcs						

C. Recommended Soldering method :

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.